

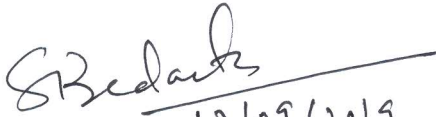
Technical Comparison of Tender No. C-001533-12-R&D-NIS-5.03-0100-18-19
for thin film deposition wafers

Company Name			Arcom enterprises	Microlabs analytical associates	Indo French HighTech	Jagatek corporation	Rashmita Traders
Sr No	Item Name	Specification	Comply?	Comply?	Comply?	Comply?	Comply?
1	MgO (100) wafer	2" dia x 0.5 mm thick, 1SP, Epi polishing wafer, Roughness 1-10 Å	Yes	Yes	Yes	Yes	Yes
2	Si (100) wafer	4" dia x 0.525 mm thick, 1 SP, p-type, B-doped, resistivities >200Ohm-cm roughness <8 Å	Yes Roughness 8 Å	No, (roughness <1.5 nm) is higher	Yes	Yes	Yes
3	LaAlO ₃ (100) wafer	2" dia x 0.5mm thick, 1 SP, orn. Epi polishing Roughness <8Å°	Yes Roughness 8 Å	didn't quote	Yes	Yes	Yes
4	Al ₂ O ₃ -Sapphire wafer-	C-plane (0001)10x10x 0.5mm, 1SP Roughness 1-10 Å,	Yes	Didn't quote	Yes	Yes	Yes
5	SrTiO ₃ (100) wafer-	1" dia. x 0.5 mm thick, epi polished wafer 1 SP Roughness<5 Å	Yes	didn't quote	Yes	Yes	Yes
6	Si with 100 nm SiO ₂ layer	Thermal oxide Wafer: 100nm SiO ₂ layer on Si (100), 4"dia x 0.525 mm thick, P type, 1SP R:1-10 Ohm-cm, Roughness<5 Å	Yes	No, the dimensions of wafer and thickness of SiO ₂ layer is not matching with our requirement.	Yes	Yes	Yes
7	Si with 100 nm SiO ₂ layer	Thermal oxide wafer: 100nm SiO ₂ Layer on Si (100), 4"dia	Yes	didn't quote	Yes	Yes	Yes

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		x 0.50mm thick, N type, 1SP R:1-10 ohm-cm Roughness<5 Å					
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Recommendation: After reviewing the technical specifications of all bidders, it is concluded that Microlabs analytical associates didn't quote for the items # 3, 4, 5, & 7, and in addition, item# 2 have high roughness and for item # 6, the dimensions of wafer and thickness of SiO₂ layer is not matching with our requirement. Therefore, their bid is rejected. The bids of all other four bidders are technically qualified. The financial bid may be opened and PO may be issued to the L1 party.



Dr. Subhankar Bedanta 12/09/2019.
(Indenting Officer, Associate Professor, SPS, NISER)